



ASETEK - Allowed U.S. Patent Claims on its RackCDU D2C™ Data Center Liquid Cooling

Thursday, April 24, 2014 - Asetek® today announced that the U.S. Patent and Trademark Office (USPTO) has issued a notice of allowance on the company's patent claims on the groundbreaking RackCDU™ Direct-to-Chip liquid cooling technology for data centers.

RackCDU D2C™ is a "free cooling" solution that captures between 60% and 80% of server heat, reducing data center cooling cost by over 50% and allowing 2.5x-5x increases in data center server density. D2C removes heat from CPUs, GPUs, memory modules within servers using water as hot as 40°C (105°F), eliminating the need for chilling to cool these components.

"Needless to say I am thrilled that we have gotten allowance on our patent claims on the RackCDU technology. Asetek's future is, to a large extent, hinging on these claims so having the exclusivity on this technology is key," says André Eriksen, Asetek's founder and CEO. "We have a solution with the potential for solving one of the largest and fastest growing energy problems on the planet and I think this has a bright future as energy consumption, density and operating costs of data centers will continue to rise."

Chilling is the largest portion of data center cooling OpEx and CapEx costs. With RackCDU D2C, less air needs to be cooled and moved by Computer Room Air Handlers (CRAH) or Computer Room Air Conditioning (CRAC) units. Furthermore, liquid cooled servers need less airflow resulting in more energy efficient servers.

RackCDU is capable of returning water from the data center at temperatures high enough to enable waste heat recycling. Data centers choosing this option recover a portion of the energy running their servers further increasing energy cost savings, reducing carbon footprint and resulting in cooling Energy Reuse Efficiencies (ERE) below 1.0.

RackCDU D2C is deployed at a rack/server level providing maximum scalability. The system consists of a zero-U rack level CDU (Cooling Distribution Unit) mounted in a 10.5 inch rack extension that includes space for 3 additional PDUs, and direct-to-chip server coolers that are drop in replacements for standard server air heat sinks.

About Asetek

Asetek is the world-leading provider of energy efficient liquid cooling systems for data centers, servers, workstations, gaming and high performance PCs. Its products are used for reducing power and greenhouse emissions, lowering acoustic noise, and achieving maximum performance by leading OEMs and channel partners around the globe.

Asetek's products are based upon its patented all-in-one liquid cooling technology with more than 1.5 million liquid cooling units deployed in the field. Founded in 2000, Asetek is headquartered in Aalborg, Denmark with offices in California, China and Taiwan. For more information, visit <http://www.asetek.com>.

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